2SD2321

Silicon NPN epitaxial planar type

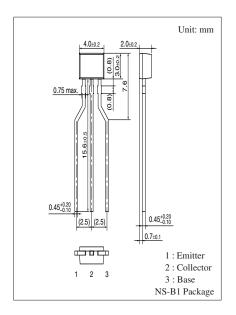
For low-frequency power amplification

■ Features

- ullet Low collector-emitter saturation voltage $V_{\text{CE(sat)}}$
- Satisfactory operation performances at high efficiency with the low-voltage power supply

■ Absolute Maximum Ratings $T_a = 25$ °C

| Parameter | Symbol | Rating | Unit | |
|---------------------------------------|------------------|-------------|------|--|
| Collector-base voltage (Emitter open) | V _{CBO} | 40 | V | |
| Collector-emitter voltage (Base open) | V _{CEO} | 20 | V | |
| Emitter-base voltage (Collector open) | V_{EBO} | 7 | V | |
| Collector current | I_C | 5 | A | |
| Peak collector current | I_{CP} | 8 | A | |
| Collector power dissipation | P_{C} | 400 | mW | |
| Junction temperature | T_j | 150 | °C | |
| Storage temperature | T_{stg} | -55 to +150 | °C | |



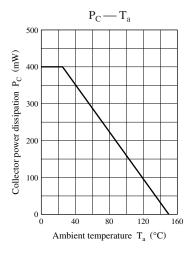
■ Electrical Characteristics $T_a = 25$ °C ± 3 °C

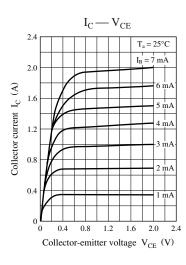
| Parameter | Symbol | Conditions | Min | Тур | Max | Unit |
|--|----------------------|---|-----|------|------|------|
| Collector-emitter voltage (Base open) | V _{CEO} | $I_C = 1 \text{ mA}, I_B = 0$ | 20 | | | V |
| Emitter-base voltage (Collector open) | V _{EBO} | $I_E = 10 \ \mu A, \ I_C = 0$ | 7 | | | V |
| Collector-base cutoff current (Emitter open) | I_{CBO} | $V_{CB} = 10 \text{ V}, I_E = 0$ | | | 0.1 | μΑ |
| Collector-emitter cutoff current (Base open) | I_{CEO} | $V_{CB} = 10 \text{ V}, I_B = 0$ | | | 1 | μΑ |
| Emitter-base cutoff current (Collector open) | I_{EBO} | $V_{EB} = 7 \text{ V}, I_C = 0$ | | | 0.1 | μΑ |
| Forward current transfer ratio | h _{FE1} * | $V_{CE} = 2 \text{ V}, I_{C} = 0.5 \text{ A}$ | 230 | | 600 | _ |
| | h _{FE2} | $V_{CE} = 2 \text{ V}, I_{C} = 2 \text{ A}$ | 150 | | | |
| Collector-emitter saturation voltage | V _{CE(sat)} | $I_C = 3 A, I_B = 0.1 A$ | | 0.28 | 1.00 | V |
| Transition frequency | f_T | $V_{CB} = 6 \text{ V}, I_E = -50 \text{ mA}, f = 200 \text{ MHz}$ | | 150 | | MHz |
| Collector output capacitance | C _{ob} | $V_{CB} = 20 \text{ V}, I_E = 0, f = 1 \text{ MHz}$ | | 26 | 50 | pF |
| (Common base, input open circuited) | | | | | | |

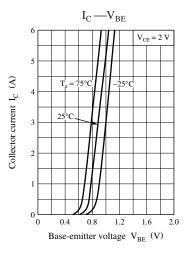
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

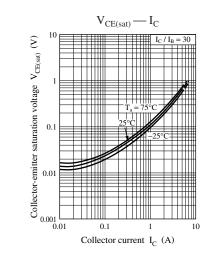
2. *: Rank classification

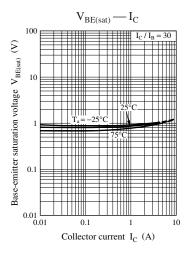
| Rank | Q | R |
|------------------|------------|------------|
| h _{FE1} | 230 to 380 | 340 to 600 |

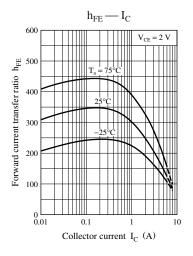


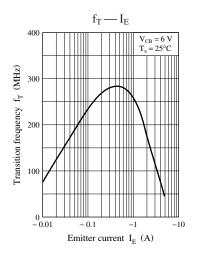


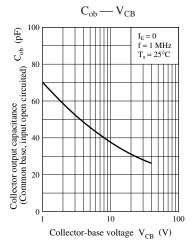


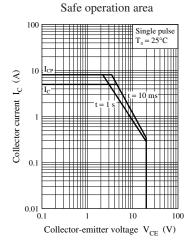












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